

EPDM20

Non-Silicone Two-Part Thermal Conductive Adhesive

LiPOLY EPDM20 is a silicone-free two-part liquid gap filler, with high viscosity and good adhesion, it can be fast cured at room temperature or elevated temperature. With a thermal conductivity of 2.2 W/m*K, EPDM20 provides high thermal conductivity and low thermal impedance. It is ideally suited for dispensing using the dispensing robot or by syringe.

■ FEATURES

- / Thermal conductivity: 2.2 W/m*K
- / Can be applied with dispenser
- / Room Temperature curing or heating curing
- / Low compression stress during assembly
- / Excellent adhesion to metal & PCB

■ TYPICAL APPLICATION

- / Electronic components: IC、CPU、MOS、Mother Board、Wireless Hub Telecom Device、Automotive electronics、Computer and peripherals
- / Between any heat-generating component and a heat sink.

■ CONFIGURATIONS

- / Cartridges: 50ml, 400ml
- / Other special and custom sizes are available upon request

■ PRESERVATION

It can be preserved for 24 months under the condition of unopened and under room temperature 25°C.

■ PLEASE NOTE

- / It is recommended to preheat the material to 40°C for 20 minutes or 50°C for 10 minutes if ambient temperature is less than 25°C for better extrusion and mixing.
- / It's recommended that the diameter of mixing tube outlet should be 3mm at least, which can solve the possible problem of poor fluidity caused by ambient temperature.

■ TYPICAL PROPERTIES

PROPERTY	EPDM20	TEST METHOD	UNIT
Color	White (A part) Black (B part)	Visual	-
Resin base	Epoxy	-	-
A:B	100:100	-	-
Viscosity A	265	DIN 53018	Pa.s
Viscosity B	252	DIN 53018	Pa.s
Density	2.7	ASTM D792	g/cm ³
Application temperature	-40~120	-	°C
Surface dry	25°C/55 min	By LiPOLY	-
Curing condition	25°C/4 hrs	By LiPOLY	-
Hardness	90	ASTM D2240	Shore A
Elongation at break	<1	ISO527	%
Tensile strength	65	ISO527	N/mm ²
Lap shear to aluminum	350	ASTM D1002	N/mm ²
Shelf life	24 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	14	ASTM D149	KV/mm
Volume resistivity	>10 ¹¹	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	2.2	ISO 22007-2	W/m*K

